

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application: Rajeev Joshi et al.	
Serial No.: 10/731,453	Confirmation No. 4432
Filed: December 9, 2003	Group Art Unit: 2891
For: WAFER-LEVEL CHIP SCALE PACKAGE AND METHOD FOR FABRICATING AND USING THE SAME	Office: Zarnecke, David A.

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION
UNDER 37 C.F.R. § 1.114

Applicant hereby files the accompanying Request for Continued Examination and, therefore, requests reconsideration of this application in light of the following amendments and remarks.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.